CLAIMS

~~[Claim 1] A method comprising:~~

~~cleaning an optical sensor head by supplying a rinsing liquid into a through-hole formed in a polishing pad on a polishing table before or after polishing of a substrate with use of slurry is performed, the optical sensor head being located below the through-hole; and~~

~~discharging the rinsing liquid from the through-hole through a drain line.~~

~~[Claim 2] The method according to claim 1, wherein the rinsing liquid is supplied into the through-hole while the through-hole is covered with a structural element.~~

~~[Claim 3] The method according to claim 2, wherein the rinsing liquid is supplied into the through-hole while the through-hole is covered with the structural element and the polishing table is stationary.~~

~~[Claim 4] The method according to claim 2, wherein the rinsing liquid is supplied into the through-hole while the through-hole is intermittently covered with the structural element and the polishing table is rotating.~~

~~[Claim 5] The method according to claim 3 or 4, wherein the structural element is a wafer.~~

~~[Claim 6] The method according to any one of claims 1 to 5, wherein the rinsing liquid is supplied into the through-hole through a liquid supply line extending in the polishing table.~~

[Claim ~~7~~1] ~~The method according to claim 1,~~A method comprising:

cleaning an optical sensor head by supplying a rinsing liquid into a through-hole formed in a polishing pad on a polishing table before or after polishing of a substrate with

use of slurry is performed, the optical sensor head being located below the through-hole; and

discharging the rinsing liquid from the through-hole through a drain line,

wherein the rinsing liquid is supplied into the through-hole from a polishing-pad cleaning nozzle arranged above the polishing pad.

[Claim ~~8~~2] ~~The method according to claim 1,~~ A method comprising:

~~wherein supplying of the rinsing liquid into the through-hole comprises~~cleaning an optical sensor head by emitting ~~the~~ a rinsing liquid toward a lower surface of a polishing-pad cleaning nozzle arranged above ~~the~~ a polishing pad, and supplying the rinsing liquid that has fallen from the lower surface of the polishing-pad cleaning nozzle into ~~the~~ a through-hole formed in the polishing pad on a polishing table before or after polishing of a substrate with use of slurry is performed, the optical sensor head being located below the through-hole; and

discharging the rinsing liquid from the through-hole through a drain line.

[Claim ~~9~~3] The method according to claim 1 or 2~~any one of claims 1 to 8~~, wherein the drain line is coupled to a drain pump configured to suck the rinsing liquid from the through-hole.